

# () insights

# Jakob Bollhalder, Head of BU Optoelectronics answers questions on the role of the

We also see different geographical approaches to the way miniaturization of devices is taking place. While Asia, mainly China, is working with existing wafer sizes and reducing device sizes step by step, Europe and North-American activities are already focused on bigger wafer sizes, semiconductor type operations and a much higher device density on the wafer.

### Q: What do you see as the biggest challenges faced in these markets over the next 5 years and how can Evatec contribute?

The biggest challenge, at least for Micro LED, in the next 5 years will be to get the wafer and production yield up to drive down costs. We also see competing technologies in the market which will also require different coating technologies. The Laser market including LIDAR applications is not so easy to predict. While customers are currently working on driving up their yield, the next years will see further applications, especially in the automotive and datacomms environment, which should also drive further investments. The challenge there is to understand when this will happen. Working in close partnership with our customers supporting both new technology and process developments remains the best way to be ready whichever direction the market heads!

## Q: What have been the highlights for BU Optoelectronics over the last 12 months and what can we expect from you in the rest of 2023 and beyond?

It's always a highlight to work so closely with so many of our customers supporting roll out of their technology roadmaps and investment in new generation coating systems. We have also been gualified by major customers for production of mini and micro LED devices. Some of them can already be purchased.

# Q: Is there any overlap with other BUs at Evatec and how do you collaborate?

Yes, definitely. This is another exciting part of my work at Evatec, looking over my shoulder to my collegues to see similar application and challenges, like particle reduction, smaller devices, improved process control etc. Besides this, many of our customers have multiple links with us addressing their different products and markets or contact with us to support their future business development.